

# ASIA PACIFIC PRINTED CIRCUIT BOARD (PCB) MARKET FORECAST 2017-2025

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## Abstracts

### KEY FINDINGS

Asia Pacific Printed Circuit Board market is expected to rise at 3.73% CAGR during the forecast period of 2017-2025. The revenue generated by the market is expected to increase from \$50956 million to \$70710 million over this period.

### MARKET INSIGHTS

The Asia-Pacific market is dominated by China. The country is currently witnessing an increase in the consumer electronics segment and the expansion of manufacturing capacity within its manufacturing companies. The Chinese government can also be rightly credited for the phenomenal market growth as it supports the market through financial subsidies and nationwide tax incentives ranging from 25 to 100 percent for qualified PCB assembly suppliers. On the other hand, the Indian market is swiftly gaining momentum and is expected to showcase the highest CAGR over the forecast period. However, the intense competition leading to falling prices, irregularity in raw material pricing and several regulations on e-waste are restraining the market growth.

### COMPETITIVE INSIGHTS

Epitome Components Ltd, Samsung Electronics Inc, Young Poong Electronics Co. Ltd, Isu Petasys, Zhen Ding Technology Holding Ltd, Nippon Mektron Ltd, Nanya Pcb Inc, AT&S, Daeduck Electronics, Shennan Circuits, Compeq Ltd, Ascent Circuit Private Limited, Hewlett-Packard Company, TTM Technologies, Ibiden Inc, Oki Printed Circuits Co. Ltd, Unimicron Technology Corp, Tripod Technology Corporation, and Hannstar Board Technology are some of the companies that are presently ruling the market.

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3. COMPEQ LTD
4. DAEDUCK ELECTRONICS
5. EPITOME COMPONENTS LTD.
6. HANNSTAR BOARD TECHNOLOGY
7. HEWLETT-PACKARD COMPANY
8. IBIDEN INC.
9. ISU PETASYS
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